

BRESD24V0M2B3MA

/ Absolute Maximum Ratings($T_a=25^\circ\text{C}$)

Parameter	Symbol	Rating	Unit
Peak Pulse Power ($t_p = 8/20\mu\text{s}$)	P_{PP}	350	W
Peak Pulse Current ($t_p = 8/20\mu\text{s}$)	I_{PP}	8.0	A
ESD per IEC 61000-4-2 (Air)	V_{ESD1}	± 30	kV
ESD per IEC 61000-4-2 (Contact)	V_{ESD2}	± 30	kV
Operating Temperature	T_{OPR}	-55 to +150	
Storage Temperature	T_{STG}	-55 to +150	

/ Electrical Characteristics($T_a=25^\circ\text{C}$)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Reverse Stand-Off Voltage	V_{RWM}				24	V
Reverse Breakdown Voltage	V_{BR}	$I_t=1\text{mA}$	26.7			V
Reverse Leakage Current	I_R	$V_{RWM}=24\text{V}$ $T=25^\circ\text{C}$			1	μA
Clamping Voltage	V_C	$I_{PP}=1.0\text{A}$ $t_p=8/20\mu\text{s}$			33	V
	V_C	$I_{PP}=8.0\text{A}$ $t_p=8/20\mu\text{s}$			44	V
Capacitance. Any I/O pin to GND	C_J	$V_R=0\text{V}$ $f=1\text{MHz}$		25	30	pF

/ Electrical Characteristic Curve

Fig.1 Non-Repetitive Pulse Power vs.Pulse Time

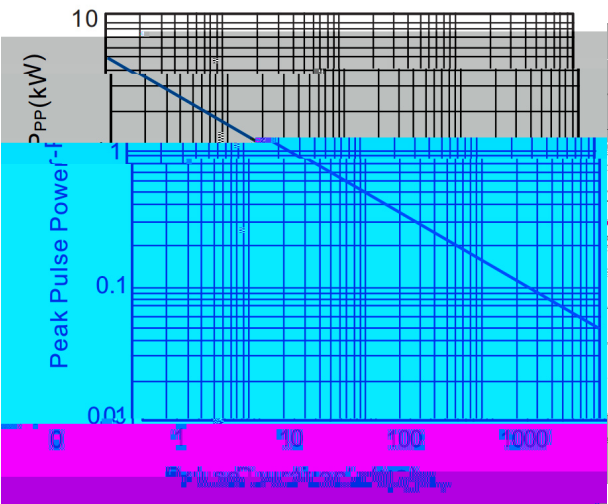
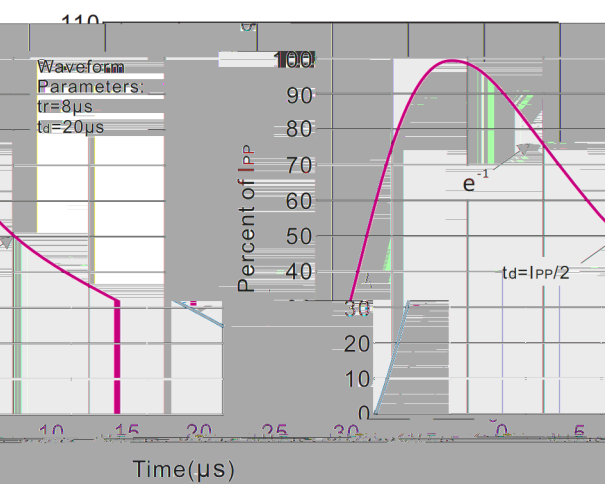


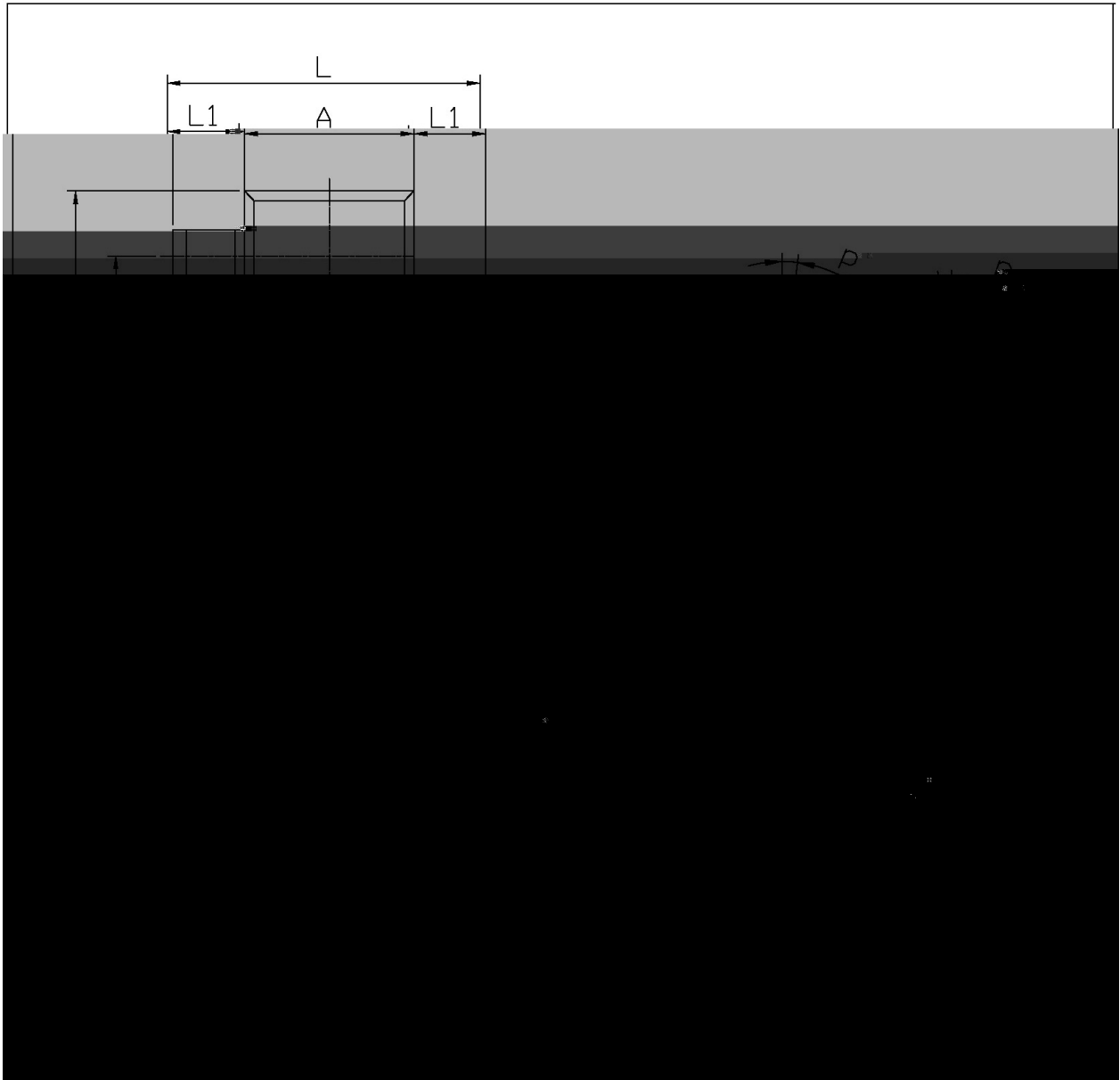
Fig.2 Pulse Waveform



/ Package Dimensions

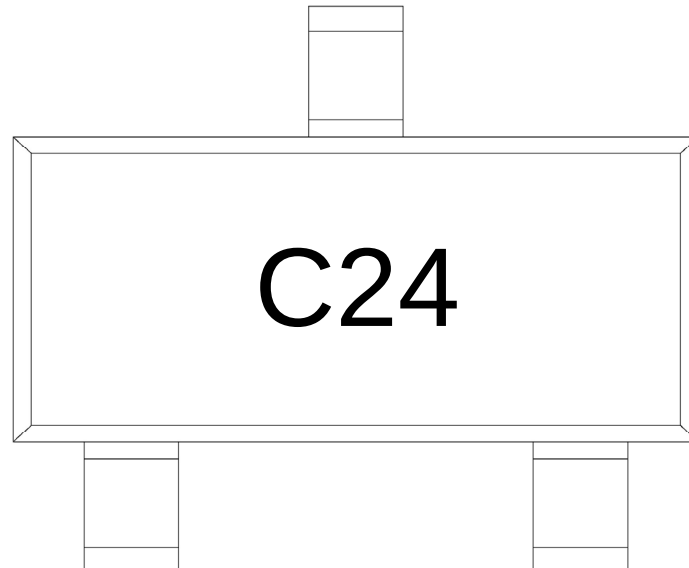
SOT-23

单位: mm





/ Marking Instructions

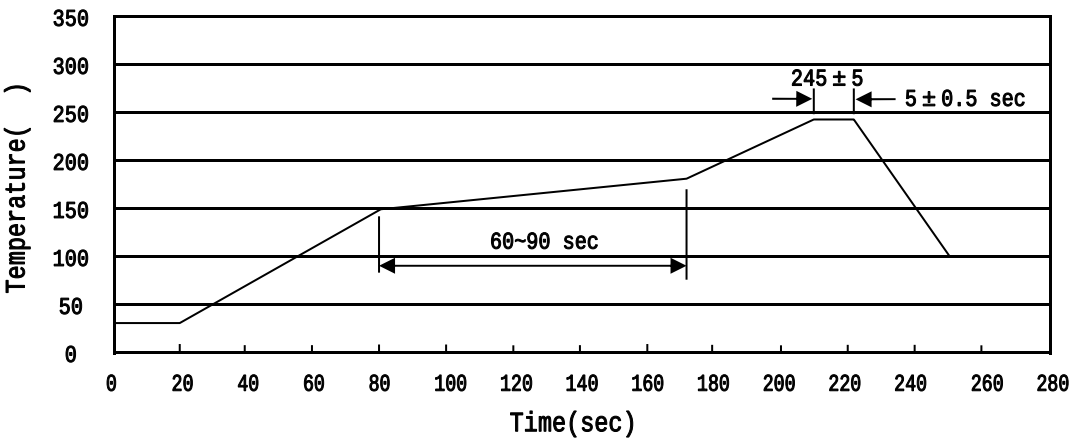


C24

Note:

C24: Product Type Code

() / Temperature Profile for IR Reflow Soldering(Pb-Free)



Note:

- 1

150 180

60 90sec;

1.Preheating:150~180 , Time:60~90sec.
- 2

245±5

5±0.5sec;

2.Peak Temp.:245±5 , Duration:5±0.5sec.
- 3

2 10 /sec.

3. Cooling Speed: 2~10 /sec.

/ Resistance to Soldering Heat Test Conditions

260±5 10±1 sec. Temp.:260±5 Time:10±1 sec

/ Packaging SPEC.

/ REEL

Package Type	Units					Dimension (unit mm ³)		
	Units/Reel	Reels/Inner Box	Units/Inner Box	Inner Boxes/Outer Box	Units/Outer Box	Reel	Inner Box	Outer Box
SOT-23	3,000	10	30,000	6	180,000	7 ×8	180×120×180	390×385×205

/ Notices